

<b>PCN Number:</b>	20210707001.1	<b>PCN Date:</b>	July 08, 2021		
<b>Title:</b>	Qualification of additional Fab site (DMOS6) and additional Assembly site (CDAT) for select LBC9 devices				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services		
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Oct 8, 2021	<b>Estimated Sample Availability:</b>	Date provided at sample request.		
<b>Change Type:</b>					
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site			
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material			
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process			
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/> Wafer Fab Site			
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials			
		<input type="checkbox"/> Wafer Fab Process			
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments is pleased to announce the qualification of an additional fab (DMOS6) and assembly site (CDAT) for selected devices as listed below in the product affected section.					
<b>Current Site</b>			<b>Additional Site</b>		
<b>Current Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>	<b>Additional Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>
RFAB	LBC9	300 mm	DMOS6	LBC9	300 mm
No material differences between Assembly sites.					
<b>Reason for Change:</b>					
Continuity of Supply					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Anticipated impact on Material Declaration</b>					
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI ECO website</a> .		
<b>Changes to product identification resulting from this PCN:</b>					
<b>Fab Site Information:</b>					
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
RFAB	RFB	USA	Richardson		
<b>DMOS6</b>	<b>DM6</b>	<b>USA</b>	<b>Dallas</b>		
<b>Assembly Site Information:</b>					
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City		
JCAP	JCP	CHN	Jiangyin		
<b>CDAT</b>	<b>CDA</b>	<b>CHN</b>	<b>Chengdu</b>		
Sample product shipping label (not actual product label)					

**TEXAS INSTRUMENTS**

MADE IN: Malaysia  
2DC: 2Q:



MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:  
ITEM: 39  
**LBL: 5A (L)T0:1750**

(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SHE (21L) CCO:USA  
(22L) ASO: MLA (23L) ACO: MYS

**Group 1 Product Affected: (Fab site offload only)**

BQ21061YFPR	BQ25157YFPR	PCM1840IRTWT	SN2252YFFR
BQ21061YFPT	BQ25882YFFR	PCMD3180IRTWR	SN2252YFFT
BQ21156RGER	BQ25882YFFT	PCMD3180IRTWT	TAS5825MRHBR
BQ21156RGET	BQ25883RGER	SN005825CRHBR	TAS5825MRHBT
BQ25150YFPR	BQ25883RGET	SN005825GRHBR	TAS5825PRHBR
BQ25150YFPT	BQ25886RGER	SN005825MRHBR	TLV320ADC3140IRTWR
BQ25151YFPR	BQ25886RGET	SN005825PRHBR	TLV320ADC3140IRTWT
BQ25151YFPT	BQ25887RGER	SN2055YFPR	TLV320ADC5140IRTWR
BQ25152YFPR	BQ25887RGET	BQ25155YFPT	TLV320ADC5140IRTWT
BQ25152YFPT	DRV5825PRHBR	SN2056YFPR	TLV320ADC6140IRTWR
BQ25155YFPR	PCM1840IRTWR	SN2056YFPT	TLV320ADC6140IRTWT

**Group 2 Product Affected: (Fab and Assembly site offload)**

TPS62800YKAR	TPS62802YKAR	TPS62806YKAT	TPS62807YKAT
TPS62801YKAR	TPS62802YKAT	TPS62807YKAR	TPS62808YKAR
TPS62801YKAT	TPS62806YKAR		



TI Information  
Selective Disclosure

## Qualification Report

Approve Date 27-May-2021  
Product Attributes

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLV320ADC5140IRTWR	QBS Process Reference: TLV62569DBV	QBS Product and Package Reference: TLV320ADC5140IRTW
AC	Autoclave, 121C, 2 atm	96 Hours	-	3/231/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	3/90/0	3/90/0
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/2400/0	-
HAST	Biased HAST, 110C/85%RH	264 Hours	-	-	1/77/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	2/154/0
HAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	3/231/0
HBM	ESD - HBM	2000 V	1/3/0	3/9/0	3/9/0
CDM	ESD - CDM	500 V	1/3/0	3/9/0	3/9/0
HTOL	Life Test, 150C	300 Hours	-	3/231/0	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/231/0	3/231/0
LU	Latch-up	(per JESD78)	1/6/0	3/18/0	1/6/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0
WBP	Wire Bond Pull	Wires	Pass	Pass	Pass
WBS	Wire Bond Shear	Wires	Pass	Pass	Pass

- Qual Device TLV320ADC5140IRTWR is qualified at LEVEL2-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

#### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green



TI Information  
Selective Disclosure

## Qualification Report

Approve Date 9-June-2021

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS62801YKAR	QBS Process Reference: TLV62569DBVR	QBS Product and Package Reference: TPS62801YKA
AC	Autoclave 121C	96 Hours	-	3/231/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	3/90/0	1/30/0
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/2400/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0
HBM	ESD - HBM	2000V	1/3/0	3/9/0	1/3/0
CDM	ESD - CDM	500V	1/3/0	3/9/0	1/3/0
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	-
HTOL	Life Test, 150C	300 Hours	-	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0
LU	Latch-up	(per JESD78 )	1/6/0	1/6/0	1/6/0
TC	Temperature Cycle, -55/125C	700 Cycles	-	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	3/231/0

- QBS: Qual By Similarity

- Qual Device TPS62801YKAR is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

#### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green



TI Information  
Selective Disclosure

## Qualification Report

Approve Date 16-June-2021

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TAS5825MRHB	QBS Process Reference: TLV62569DBVR	QBS Package Reference: TPS53641RSBR	QBS Package Reference: BQ294504DRVR
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	3/90/0	-	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/2400/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-	3/231/0
HBM	ESD - HBM	2000 V	1/3/0	3/9/0	-	-
CDM	ESD - CDM	500 V	1/3/0	3/9/0	-	-
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	-	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	3/231/0	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0	-
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0

- QBS: Qual By Similarity
  - Qual Device TAS5825MRHB is qualified at LEVEL2-260C
  - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
  - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
  - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
- Green/Pb-free Status:**  
Qualified Pb-Free(SMT) and Green



TI Information  
Selective Disclosure

## Qualification Report

Approve Date 21-June-2021

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: BQ25150YFPT	Qual Device: BQ21061YFPR	QBS Process Reference: TLV62569DBVR	QBS Package Reference: TPS62801YKA
AC	Autoclave 121C	96 Hours	-	-	3/231/0	-
ED	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	1/30/0
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	3/2400/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	3/231/0
HBM	ESD - HBM	2000V	1/3/0	-	3/9/0	1/3/0
CDM	ESD - CDM	500V	1/3/0	-	3/9/0	1/3/0
HTOL	Life Test, 125C	1000 Hours	-	-	3/231/0	-
HTOL	Life Test, 150C	300 Hours	-	-	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	3/231/0
LU	Latch-up	(per JESD78)	1/6/0	-	1/6/0	1/6/0
TC	Temperature Cycle, -55/125C	700 Cycles	-	-	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0

- QBS: Qual By Similarity
  - Qual Device BQ25150YFPT is qualified at LEVEL1-260C
  - Qual Device BQ21061YFPR is qualified at LEVEL1-260C
  - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
  - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
  - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
- Green/Pb-free Status:**  
Qualified Pb-Free(SMT) and Green



## Qualification Report

Approve Date 24-June-2021

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: BQ25883RGER	QBS Process Reference: TLV62569DBVR	QBS Package Reference: TPS53641RSBR	QBS Package Reference: BQ294504DRVR
AC	Autoclave 121C	96 Hours	-	3/231/0	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	3/90/0	-	-
	Early Life Failure Rate, 125C	48 Hours	-	3/2400/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-	3/231/0
HBM	ESD - HBM	2000 V	1/3/0	3/9/0	-	-
CDM	ESD - CDM	250 V	1/3/0	3/9/0	-	-
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	-	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	3/231/0	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0	-
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0

- QBS: Qual by Similarity

- Qual Device BQ25883RGER is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free (SMT) and Green



## Qualification Report

Approve Date 24-June-2021

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: BQ25882YFFR	QBS Process Reference: TLV62569DBVR	QBS Product and Package Reference: BQ25150YFFT
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	3/90/0	Pass
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/2400/0	3/3000/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0
HBM	ESD - HBM	2000 V	1/3/0	3/9/0	-
CDM	ESD - CDM	500 V	1/3/0	3/9/0	-
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	-
HTOL	Life Test, 150C	300 Hours	-	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0

- QBS: Qual By Similarity

- Qual Device BQ25882YFFR is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

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**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
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